# 2SD0968A (2SD968A)

### Silicon NPN epitaxial planar type

For low-frequency driver amplification Complementary to 2SB0789A (2SB789A)

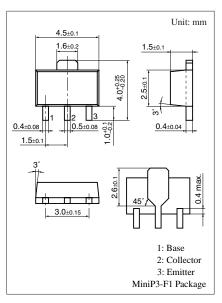
#### ■ Features

- ullet High collector to emitter voltage  $V_{\text{CEO}}$
- Large collector power dissipation P<sub>C</sub>
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	V <sub>CBO</sub>	120	V
Collector to emitter voltage	V <sub>CEO</sub>	120	V
Emitter to base voltage	$V_{EBO}$	5	V
Peak collector current	$I_{CP}$	1	A
Collector current	$I_{C}$	0.5	A
Collector power dissipation *	P <sub>C</sub>	1	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

Note) \*: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion



Marking symbol: V

### ■ Electrical Characteristics $T_a = 25$ °C

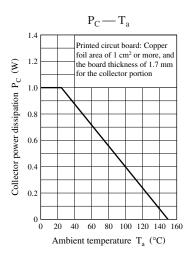
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector to emitter voltage	$V_{CEO}$	$I_C = 100 \ \mu A, I_B = 0$	120			V
Emitter to base voltage	$V_{EBO}$	$I_E = 10 \ \mu A, \ I_C = 0$	5			V
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	130		330	
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50	100		
Collector to emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.6	V
Base to emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.2	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	20	pF

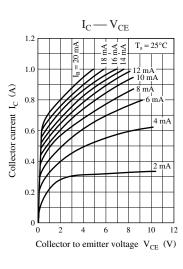
Note) \*1: Pulse measurement

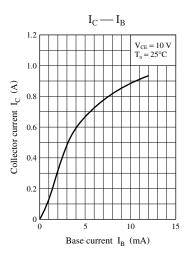
\*2: hFE Rank classification

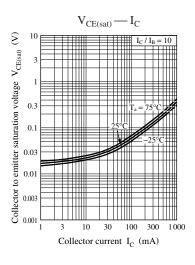
Rank	R	S
h <sub>FE1</sub>	130 to 220	185 to 330
Marking symbol	VR	VS

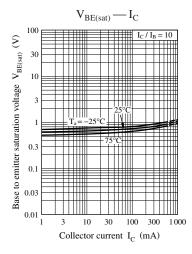
Note) The part number in the parenthesis shows conventional part number.

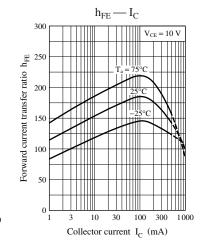


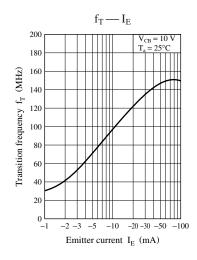


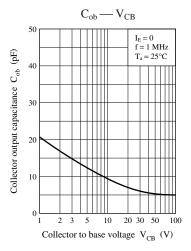












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